


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	AMS/23/14247
1.3 Title of PCN	LSM6DSV family: Asic transfer to AG300 FAB.
1.4 Product Category	Pls refer to the Products list.
1.5 Issue date	2023-07-28

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Andrea Mario ONETTI
2.1.2 Marketing Manager	Simone FERRI
2.1.3 Quality Manager	Michele CALDERONI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ST Rousset, TSMC Taiwan, ST AG300 as diffusion plants.

4. Description of change

	Old	New
4.1 Description	ASIC wafer for Suwon 3.0 diffused in Rousset and TSMC fabs.	ASIC wafer for Suwon 3.0 diffused in Rousset, TSMC and AG300 fabs.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	ASIC transfer is to gain capacity improvement.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated FG code
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7. Timing / schedule

7.1 Date of qualification results	2023-11-06
7.2 Intended start of delivery	2024-01-08
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

14247 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LSM6DSV16XTR	

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